



Microprobe Metrology for direct Sheet Resistance and Mobility characterization

Peter Folmer Nielsen

VP, Director of R & D and Technical Sales

Co-Founder

Capres A/S

Dirch H. Petersen , Rong Lin, Ane Jensen, Henrik H. Henrichsen,
Lauge Gammelgaard, Daniel Kjær, Ole Hansen



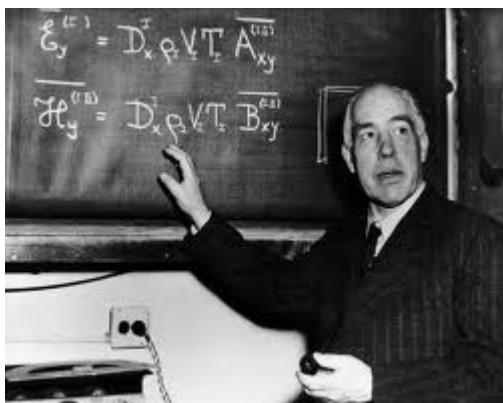
DTU Nanotech
Department of Micro- and Nanotechnology



Denmark....The land of....



Hans Christian Andersen



Niels Bohr

Micro and Nanoscale Electrical Probing
CAPRES 2012



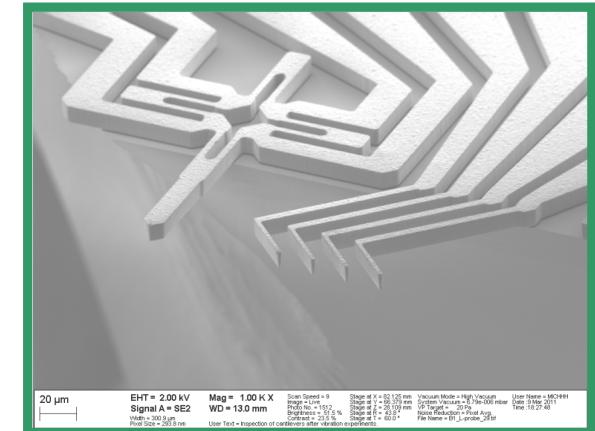
Danish Pastry



Danish Bacon

AND

**Microscopic
Multi Cantilever
Probes**





You've never seen a multi point probe like this before...

Photo by Peter F Nielsen @ Northeast Greenland



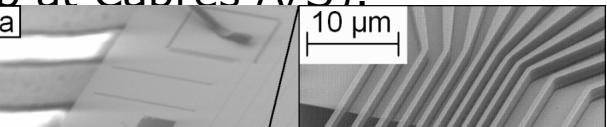
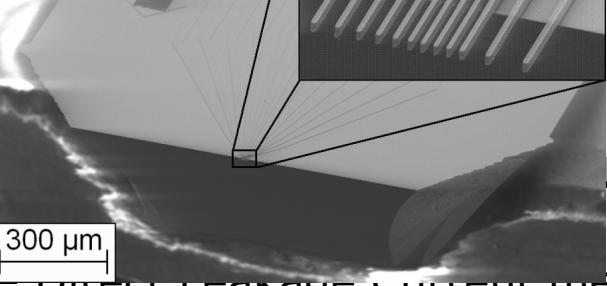


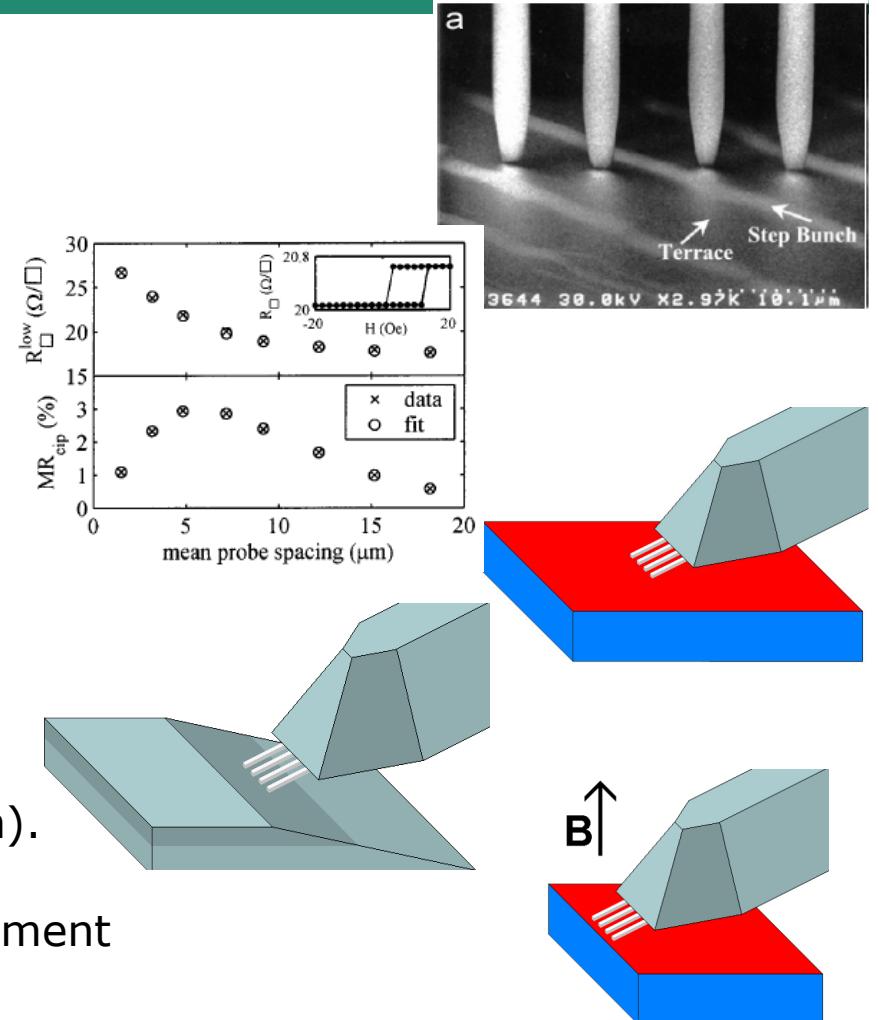
Outline

- History
- Sheet resistance (Micro Four Point Probe , M4PP)
 - Microprobes and Basic Tool requirements
 - Dual configuration, Small samples, Fundamental limitations
 - Application
- Micro Hall effect
 - Basic Hall-Effect Measurement and Hall-effect measurement using a Collinear M4PP
 - Applications
- Capres Fact-Sheet, Conclusion and Discussion



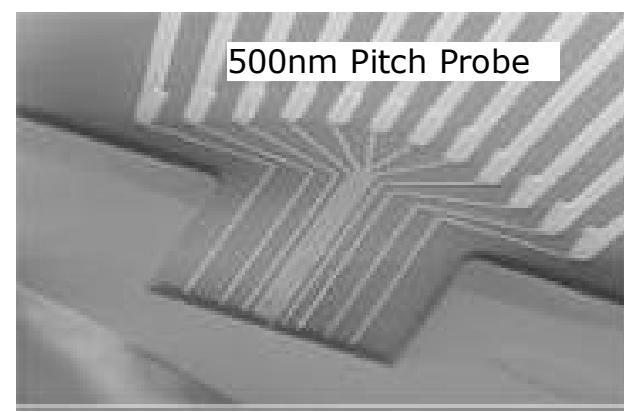
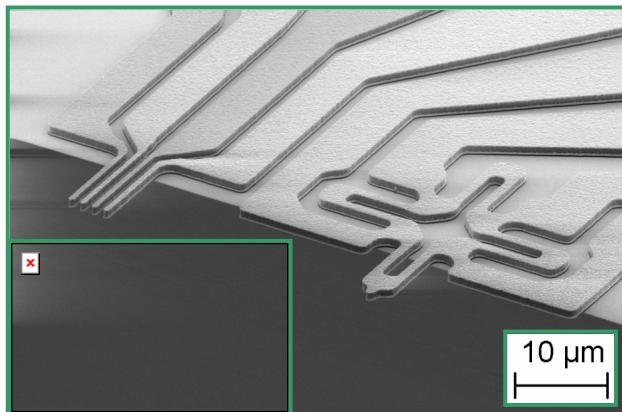
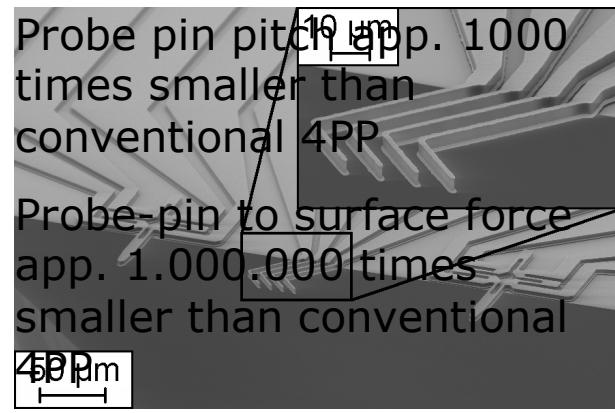
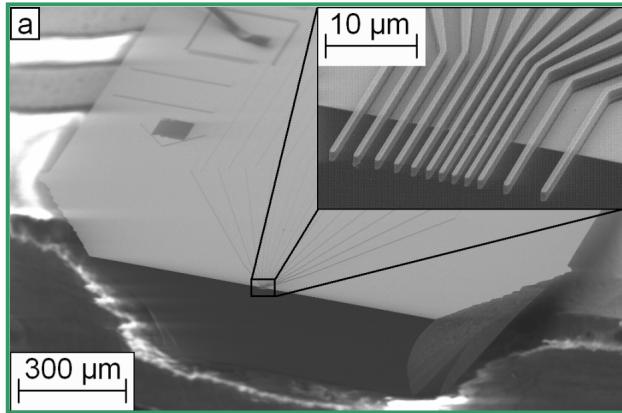
History

- 1999-2000 First M4PP developed and Capres A/S Founded
- 2003 – Magnetic tunnel junction characterization.
(D.C.Worledge, et al.)
- 2005 – USJ R_s characterization
(Group at Capres A/S).

- 2006
(T. Cl)
- 2008
(D.H. Nielsen).
- 2012
Direct Leakage Current measurement
(Rong Lin et. al at IIT 2012).






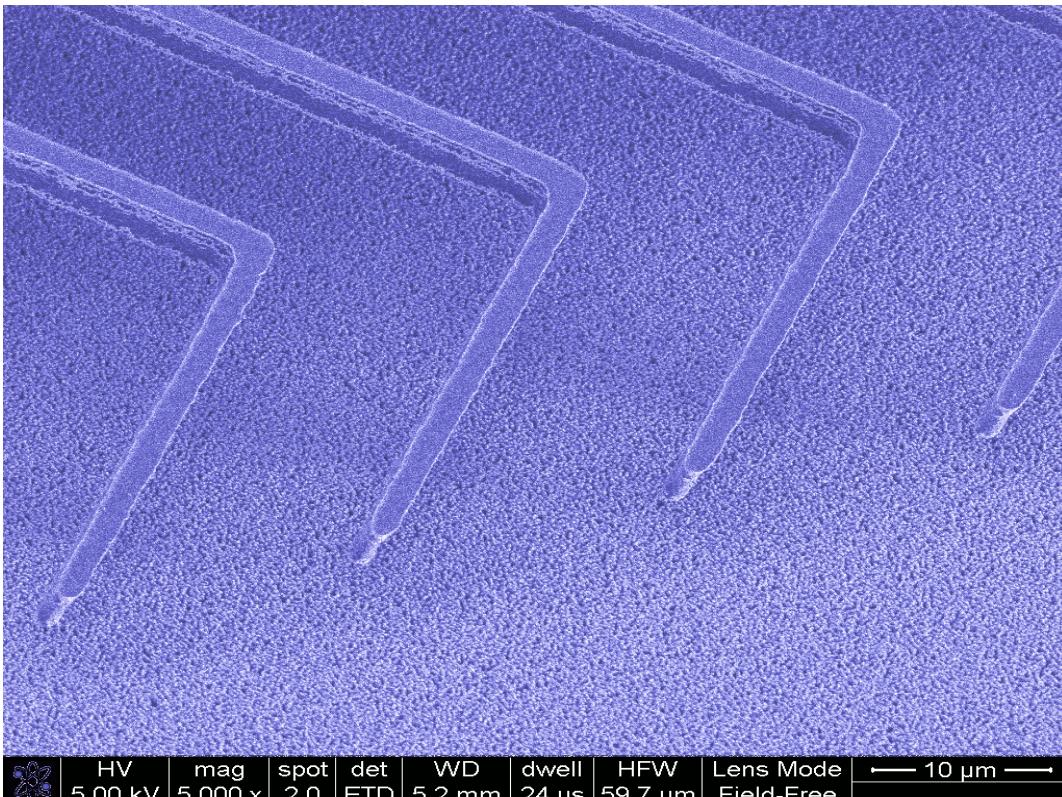
Microscopic Multicantilever Probes M4PP & M12PP





Microscopic Multicantilever Probes M4PP & M12PP

3D Ultra Flexible Microprobe with integrated "Strain Gauge" cantilever for surface detection.



Static contact to surface during measurement.

- Can be used in noisy environment

Increased probe "lifetime".

- More than 2000 measurements per. probe

No surface layer penetration.

- < 2nm layers can be measured

No surface contamination

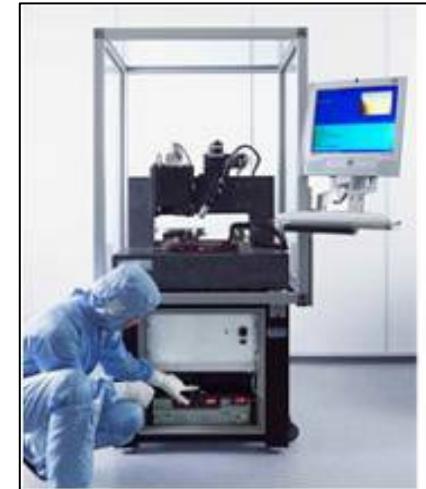
- Level much lower than Tier 1 fab. requirements

	HV 5.00 kV	mag 5 000 x	spot 2.0	det ETD	WD 5.2 mm	dwell 24 µs	HFW 59.7 µm	Lens Mode Field-Free	10 µm
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Basic Tool requirements needed to do measurements using Microscopic Multicantilever Probes

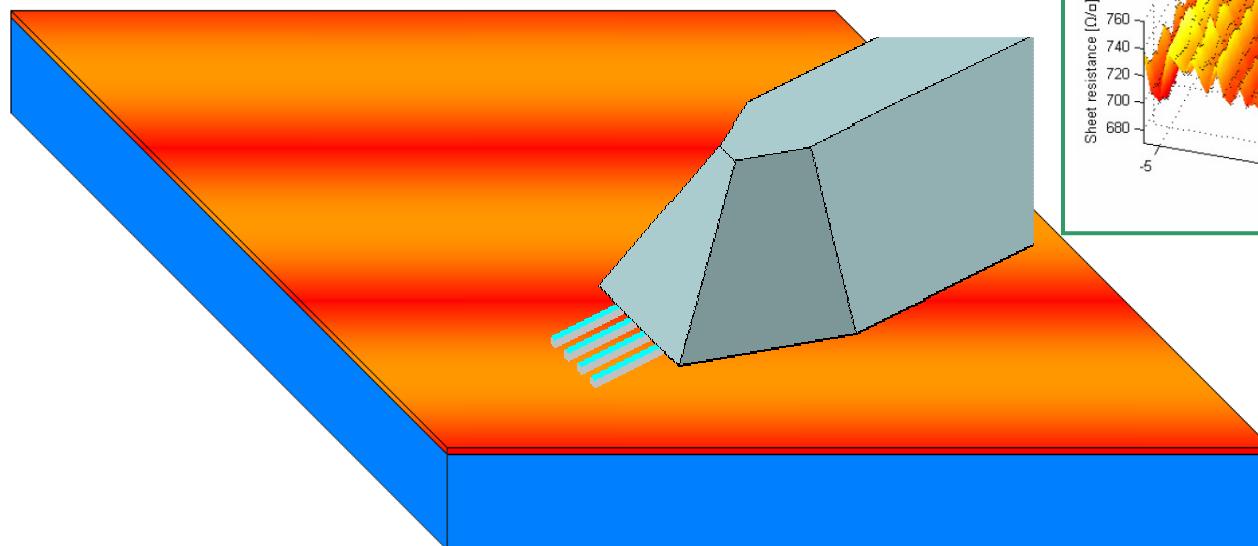
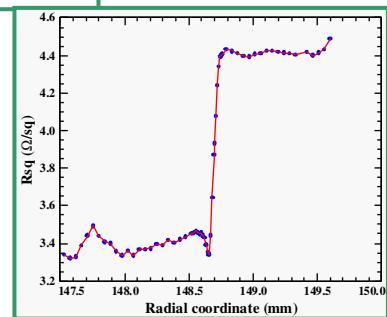
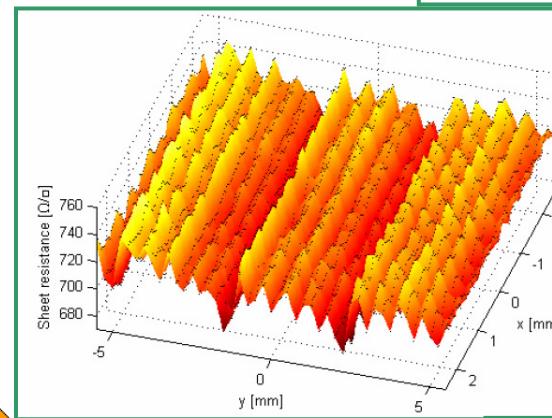
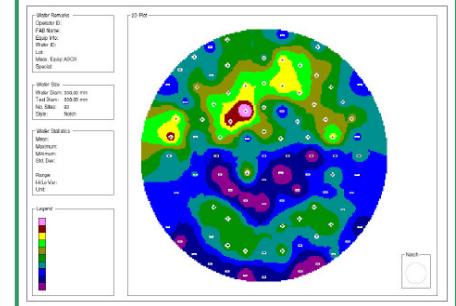
- High resolution air-bearing X-Y-Z stage for probe positioning (Smallest step size is <50nm)
- Ultra high in-position stability (< 10nm jitter)
- Antivibration system
- X-Y travel range up to 300mm (450mm planned)
- Ultra low noise front end electronics with build-in multiplexer for probe pin configuration setting
- Automatic probe exchange mechanism for use in the fully automatic MicroRSP-A300 tool
- Dual optical system for pattern recognition and probe pin position feedback (resolution <1 um)
- Software with build in functionality to measure Rs and Hall-mobility on small samples and patterned 300mm product wafers





Measurements using Microscopic Multicantilever Probes

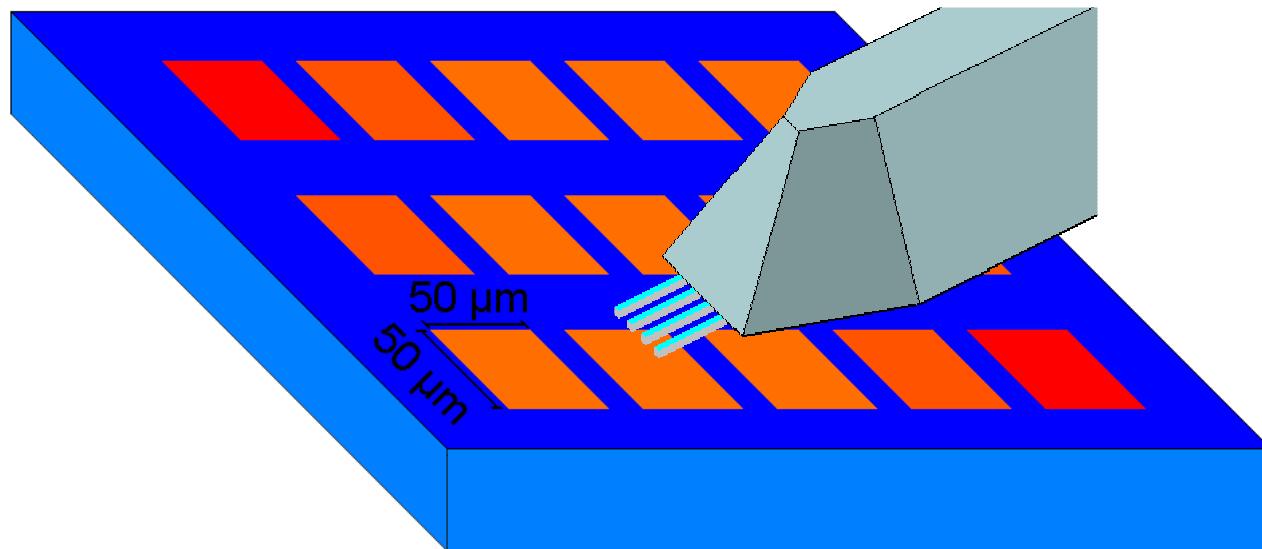
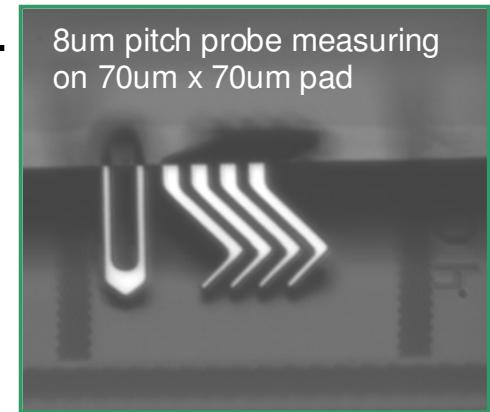
- Accurate R_s mapping. (Reproducibility and repeatability: <0.1 %)
- High spatial resolution. (Probe pitch down to 500nm)
- Measurements on ultrathin conducting layers (< 2nm layer thickness)
- No edge exclusion (Zero (0) edge exclusion)





Measurements using Microscopic Multicantilever Probes

- Accurate In-line measurements directly on product wafers.
- Accurate *Rs, Mobility and Active Carrier Density measurements* on small pads.

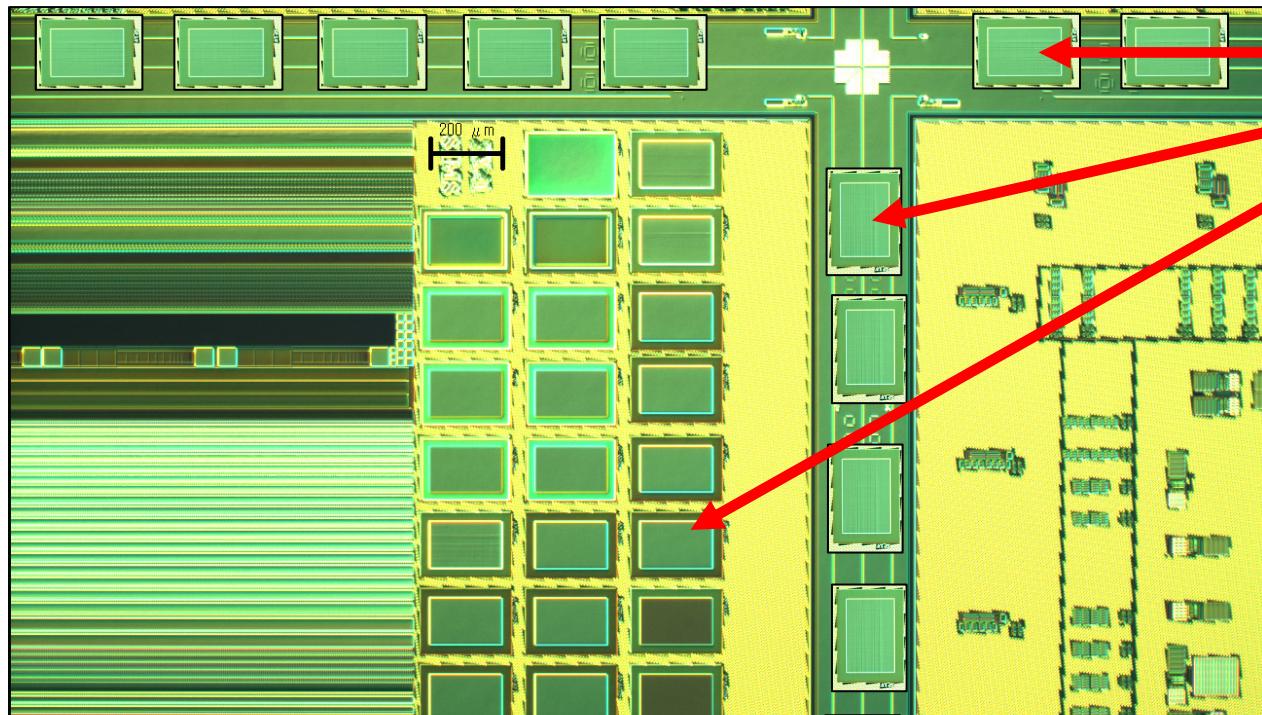


Automatic probing
on pads down to
50um x 50um

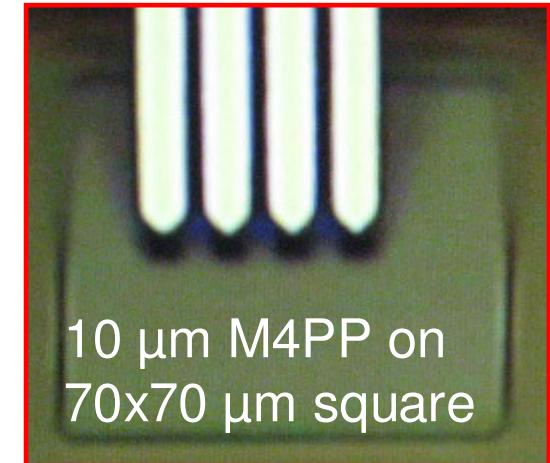


Measurements using Microscopic Multicantilever Probes

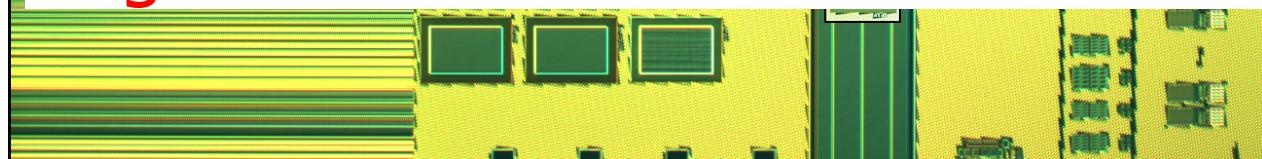
Direct R_s and Hall mobility measurements on product wafers



**Test pads in scribe
lines or test die
area**

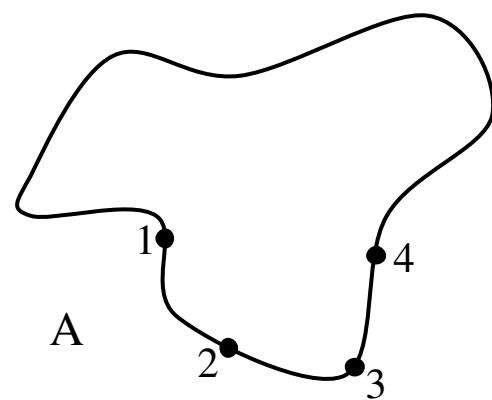


Edge-effect introduce error in R_s -measurement





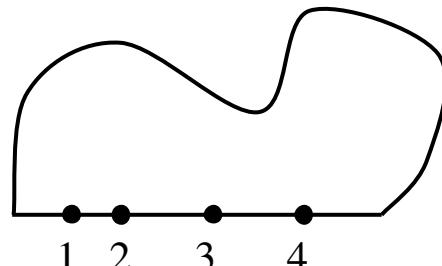
Dual configuration – small samples



A

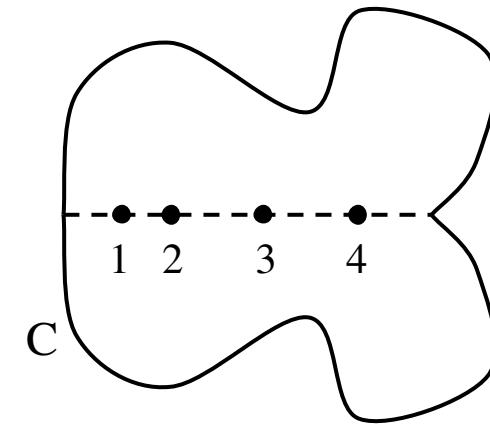
$$R_a = V_{23}/I_{14}$$

$$R_b = V_{24}/I_{13}$$



B

**Exact measurements
on mirror planes!**



C

$$R_A = V_{23}/I_{14}$$

$$R_B = V_{24}/I_{13}$$

$$e^{\frac{2\pi R_A}{R_\square}} - e^{\frac{2\pi R_B}{R_\square}} = 1$$

R. Rymaszewski, J. Phys. (1969)

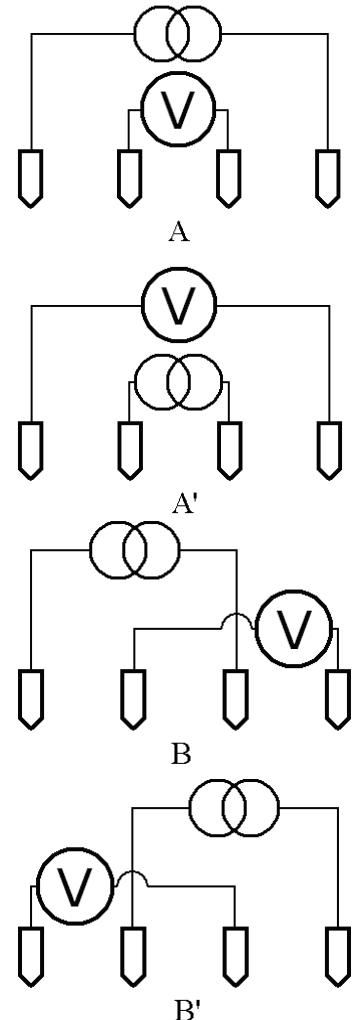
$$e^{\frac{\pi R_a}{R_\square}} - e^{\frac{\pi R_b}{R_\square}} = 1$$

L.J. van der Pauw,
Philips Res. Rep. (1958).

S. Thorsteinsson, et al.
Rev. Sci. Instrum. (2009).



Dual configuration – small samples



Resistance difference

$$\Delta R_{AA'} \equiv R_A - R_{A'}$$

Resistance average

$$\overline{R}_{AA'} \equiv \frac{R_A + R_{A'}}{2}$$

Resistance difference

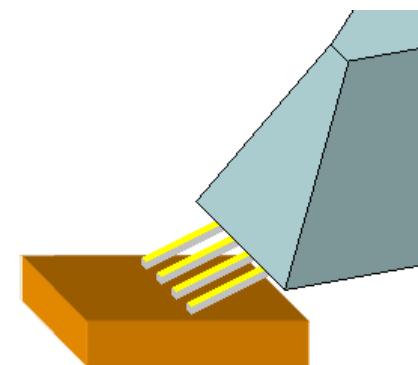
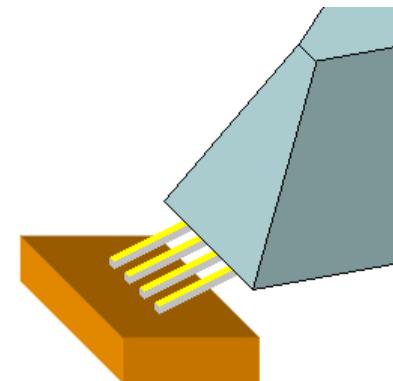
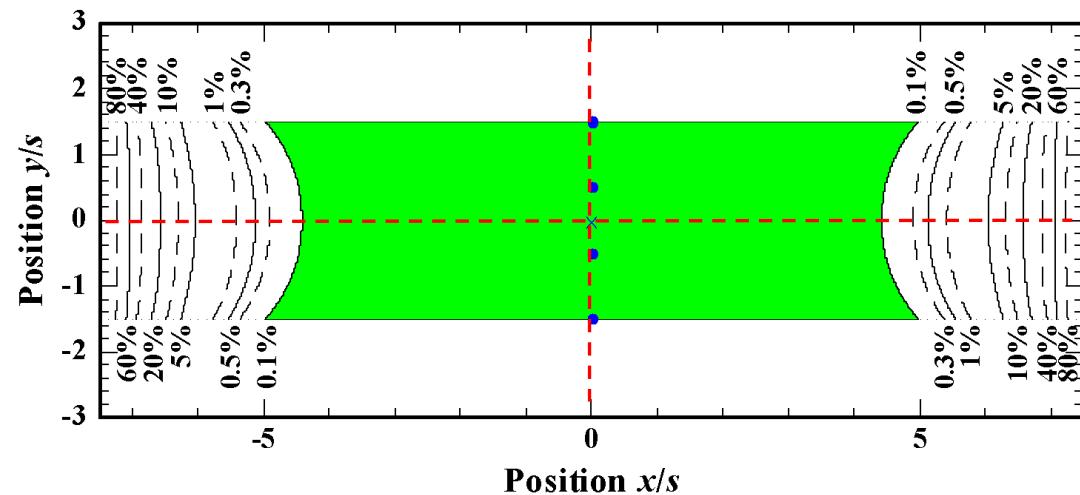
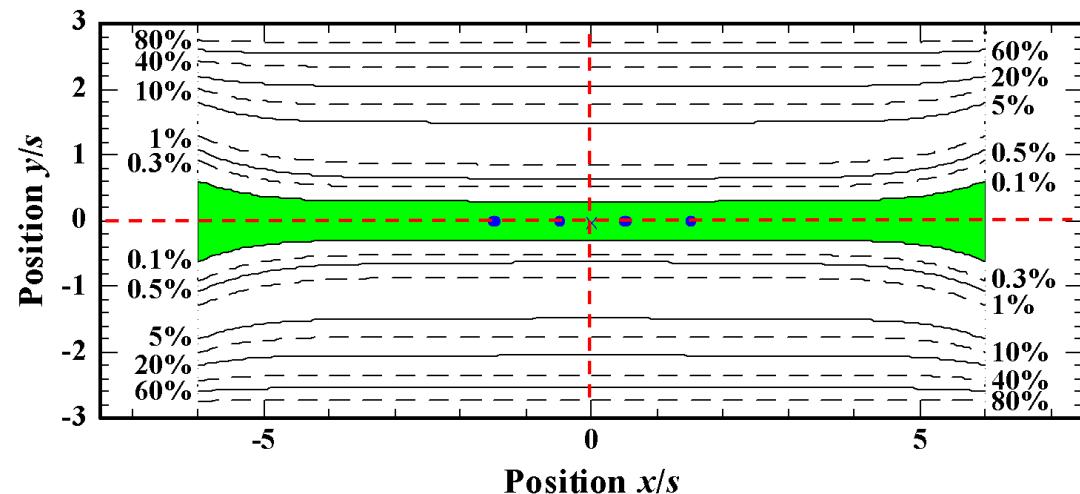
$$\Delta R_{BB'} \equiv R_B - R_{B'}$$

Resistance average

$$\overline{R}_{BB'} \equiv \frac{R_B + R_{B'}}{2}$$



Dual configuration – small samples



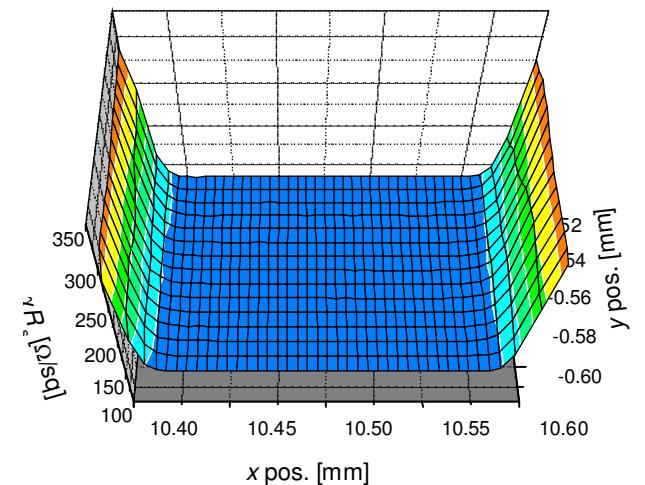
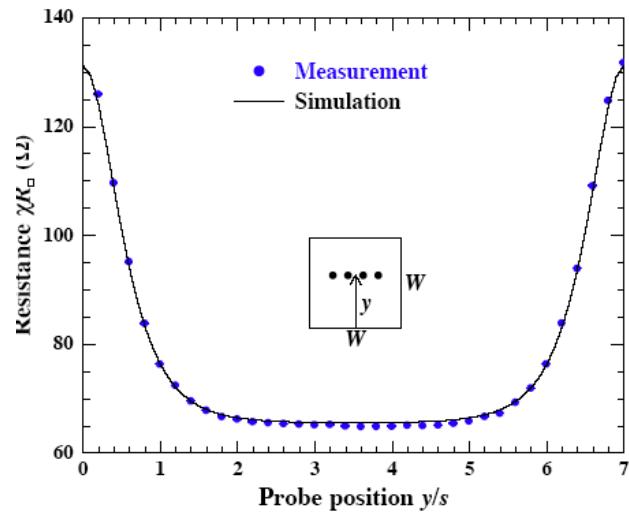
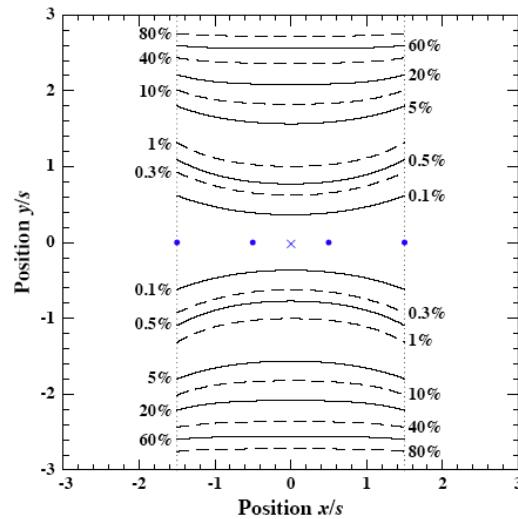
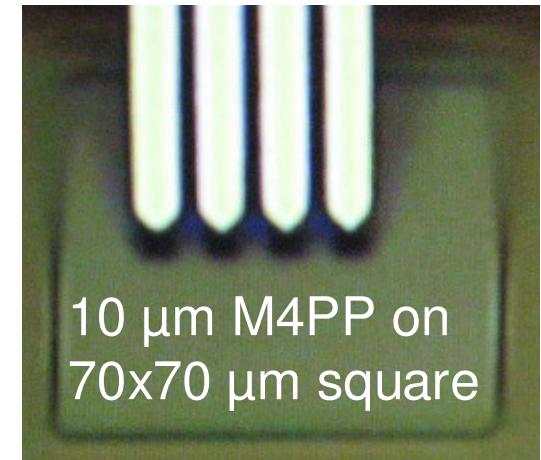
S. Thorsteinsson, et al. Rev.
Sci. Instrum. (2009).



Dual configuration – small samples

Product Wafer Monitoring *Scribe-line and test area pads*

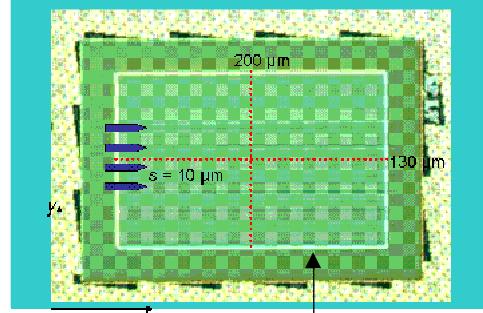
10 μm M4PP using dual-configuration R_s measurements with a $\pm 2.5 \mu\text{m}$ alignment accuracy, can easily achieve $<0.1\%$ offset errors on a $50 \times 50 \mu\text{m}$ pads.



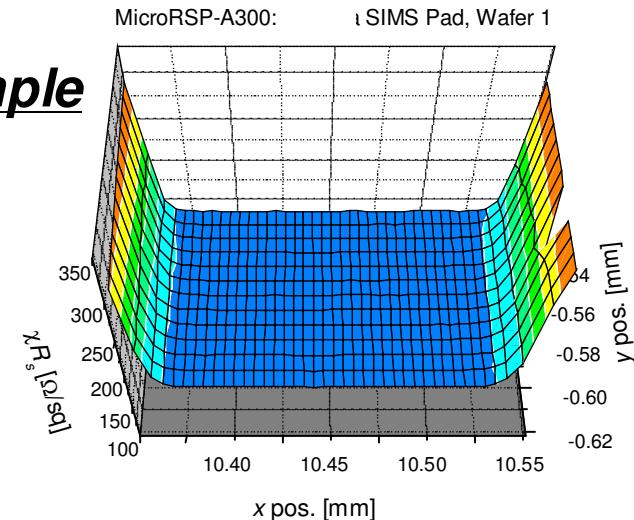


Dual configuration – small samples

Measurement example

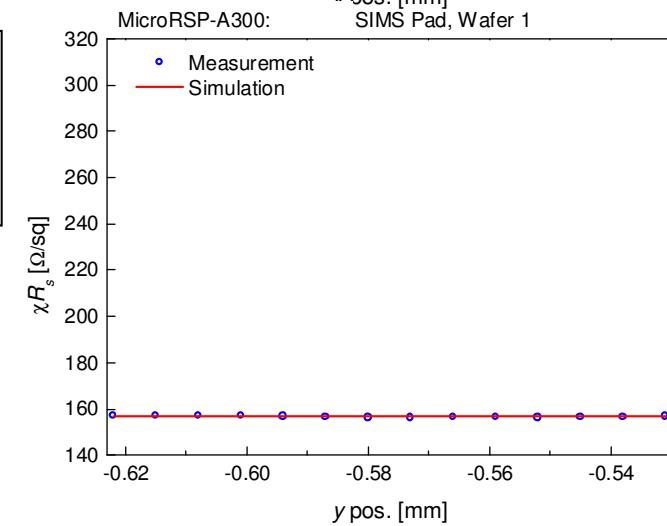
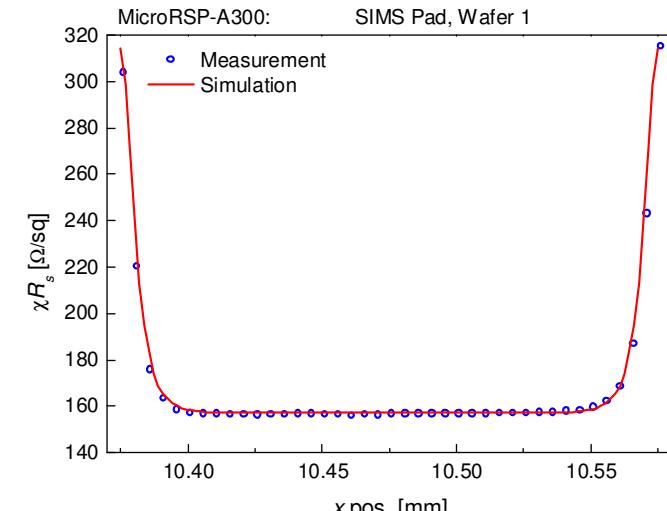


SIMS pad



Rs area map and X-Y
line scans measured
directly on SIMS pad

Capres' microRSP-A300 tool and probing technology enables direct Rs measurement on pads and small structures on patterned and un-patterned production wafers



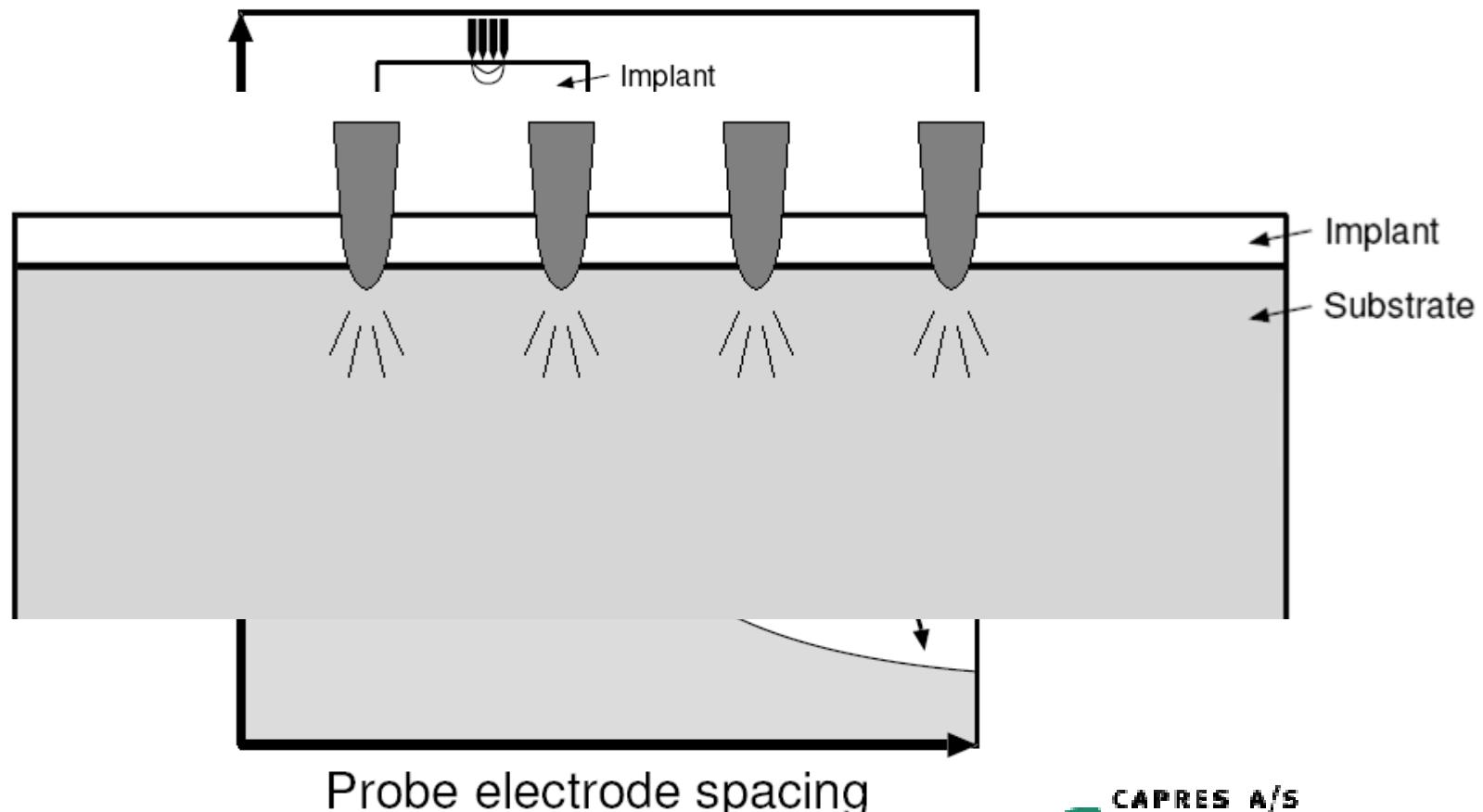
CAPRES A/S

Capres A/S is a registered



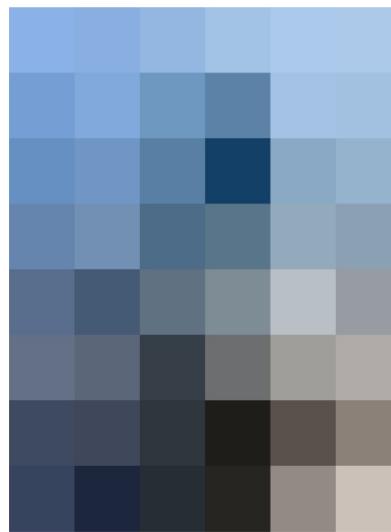
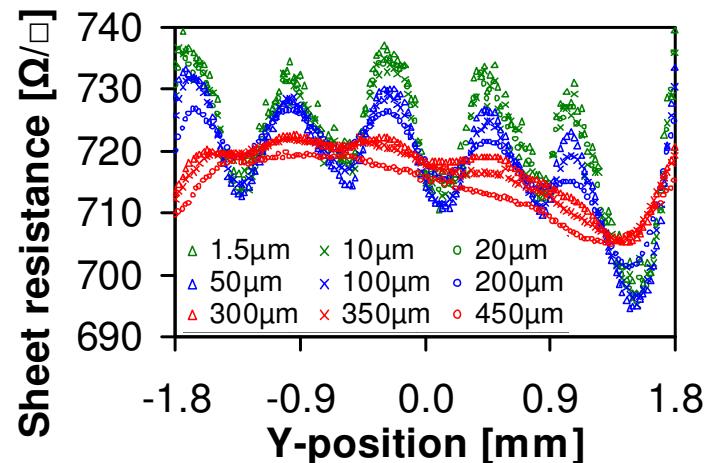
Fundamental limitation Need soft probes with small probe pin pitch to do correct R_s measurements

- Single conductive sheet
 - Probe penetration
 - Junction leakage

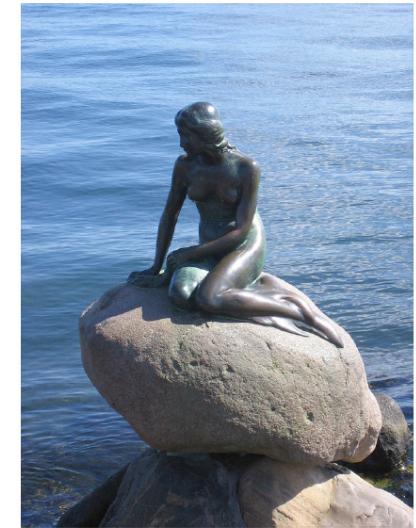




Effect of probe pitch & Resolution matters



6 by 8 pixels



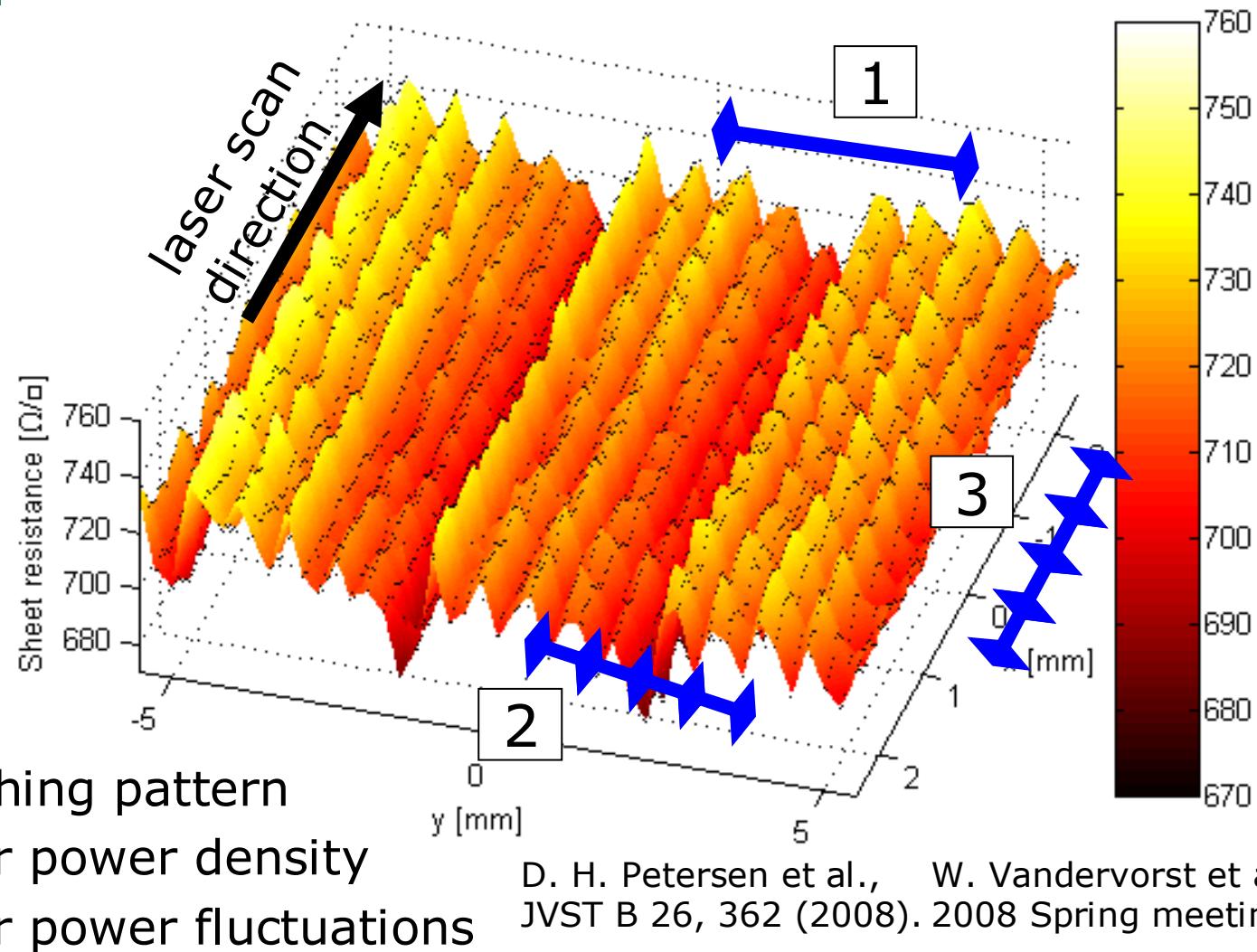
600 by 800 pixels

Macroscopic four-point probes clearly underestimates R_s variations.
Resolution matters

D. H. Petersen et al., JVST B 26, 2008.



Micro R_s variations





Hall-mobility Measure Rs using a collinear 4PP and extract Mobility and Active Carrier Density

$$R_S = \frac{1}{e\bar{\mu}_H N_{HS}}$$

$$N_{HS} = \left| \frac{B_z I}{e V_H} \right|$$

$$\bar{\mu}_H = \left| \frac{V_H}{B_z R_S I} \right|$$

$$\frac{V_H}{I} \equiv \frac{B_z}{Z e N_{HS}}$$

Notation

e = unit charge. (constant)

Z = carrier charge ($Z = \pm 1$).

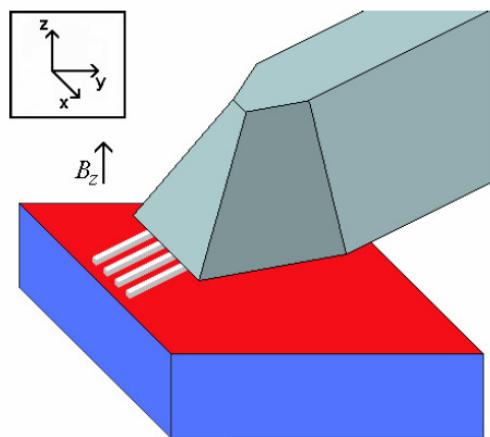
B_z = magnetic flux density. (constant)

N_{HS} = Hall Sheet Carrier Density.

$\bar{\mu}_H$ = Average Hall Mobility.

V_H = Measured Hall Voltage

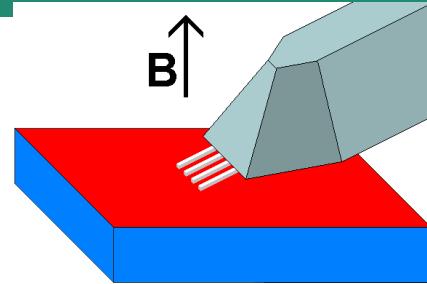
I = Applied measurement current



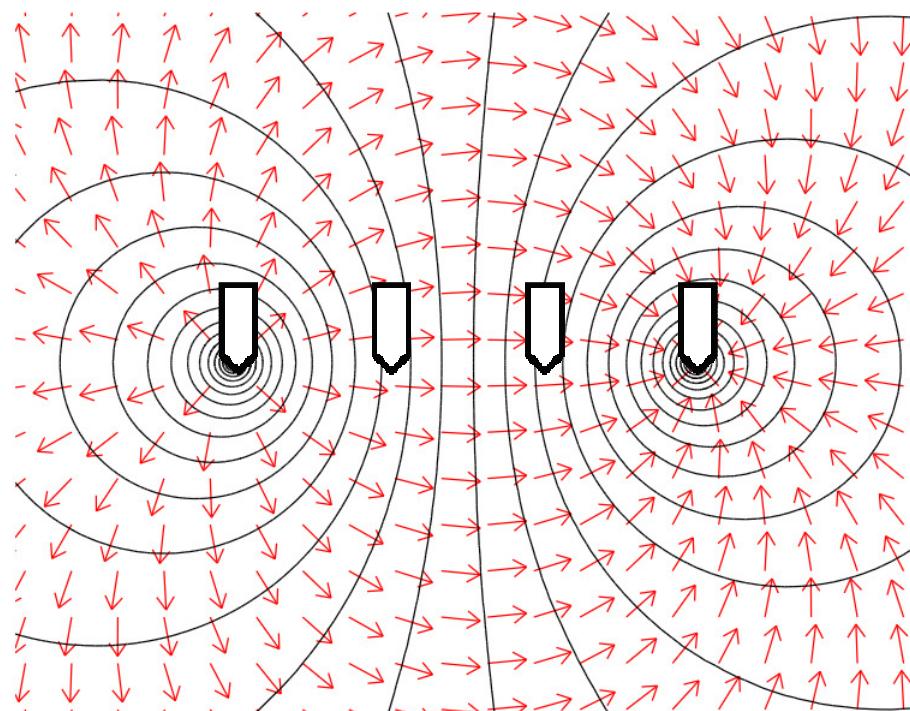
Micro and Nanoscale Electrical Probing
CAPRES 2012



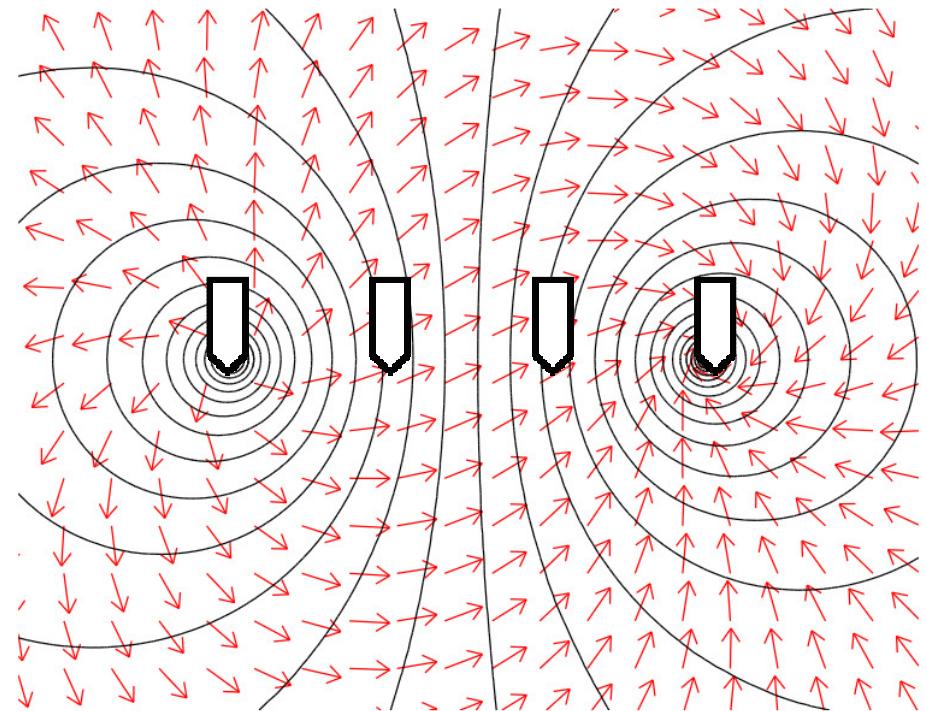
Infinite sheet: No Hall Effect



$B = 0$
Purely radial current

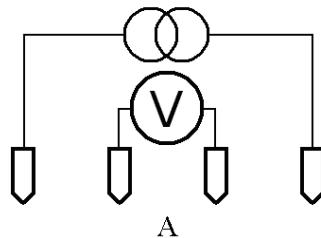


$B \neq 0$
Tangential current



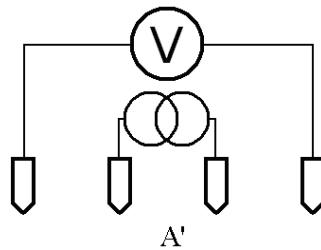


Micro Hall effect



Resistance difference

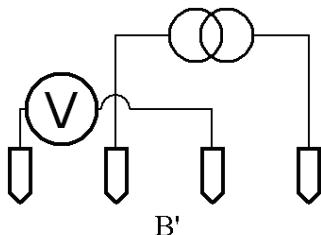
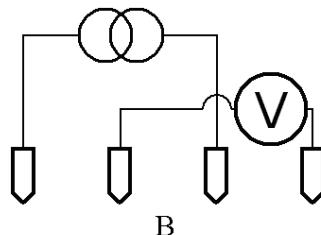
$$\Delta R_{AA'} \equiv R_A - R_{A'} = 0$$



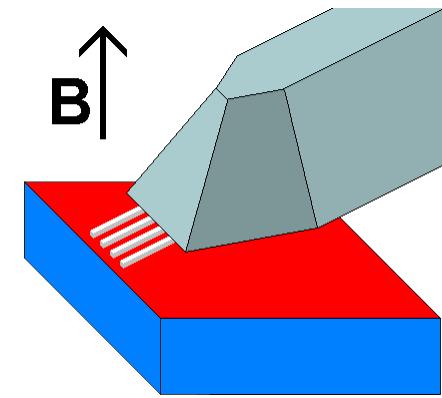
Resistance average

$$\overline{R}_{AA'} \equiv \frac{R_A + R_{A'}}{2} = c_A R_S$$

$$\overline{R}_{BB'} \equiv \frac{R_B + R_{B'}}{2} = c_B R_S$$



D.H. Petersen, et al.,
J. Appl. Phys. (2008).



Mobility

$$\bar{\mu} = \frac{Z R_H}{r_H R_S B_z}$$

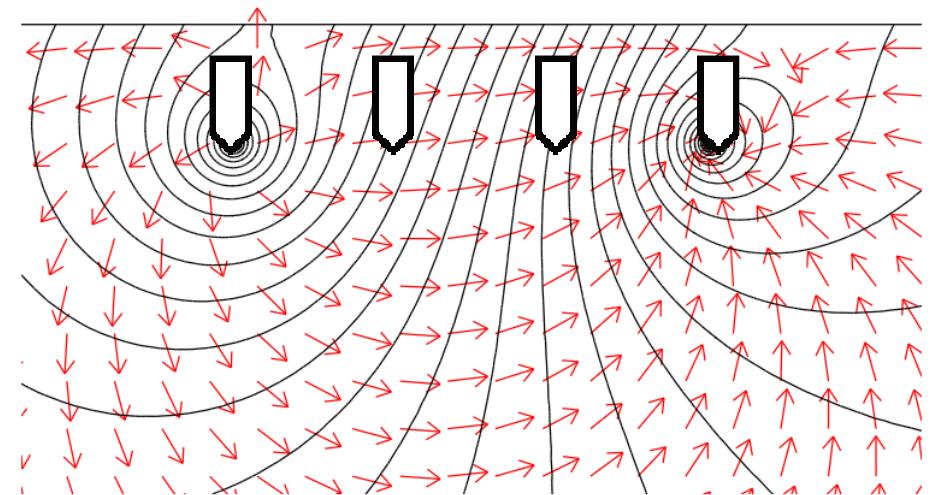
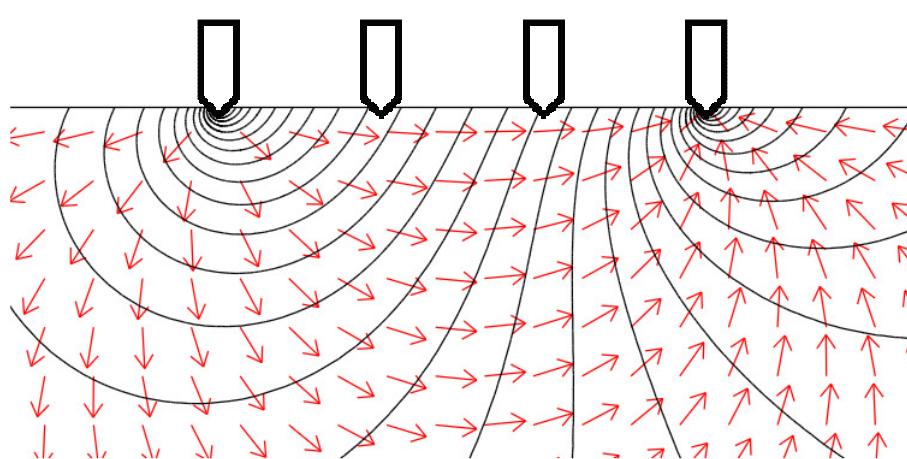
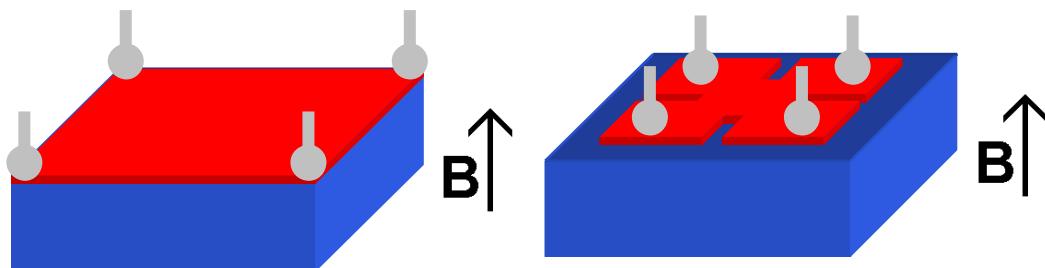
Sheet carrier density

$$N_S = \frac{r_H B_z}{Z e R_H}$$



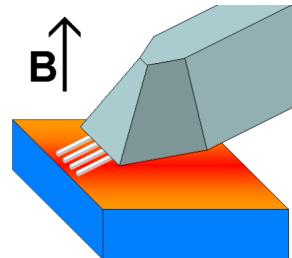
Single barrier: Hall effect

Conventional Hall effect
(van der Pauw)



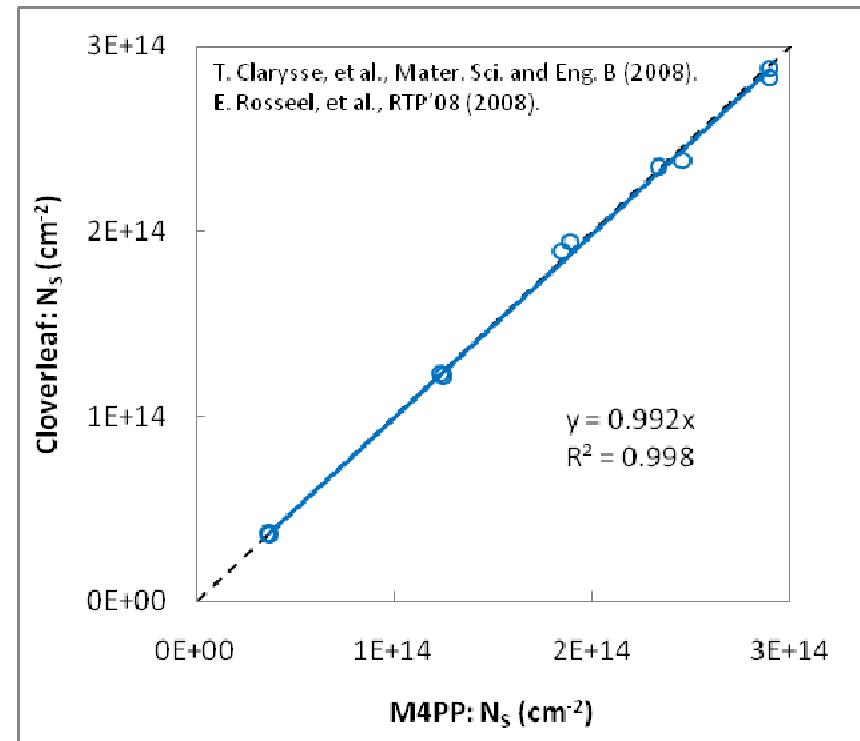
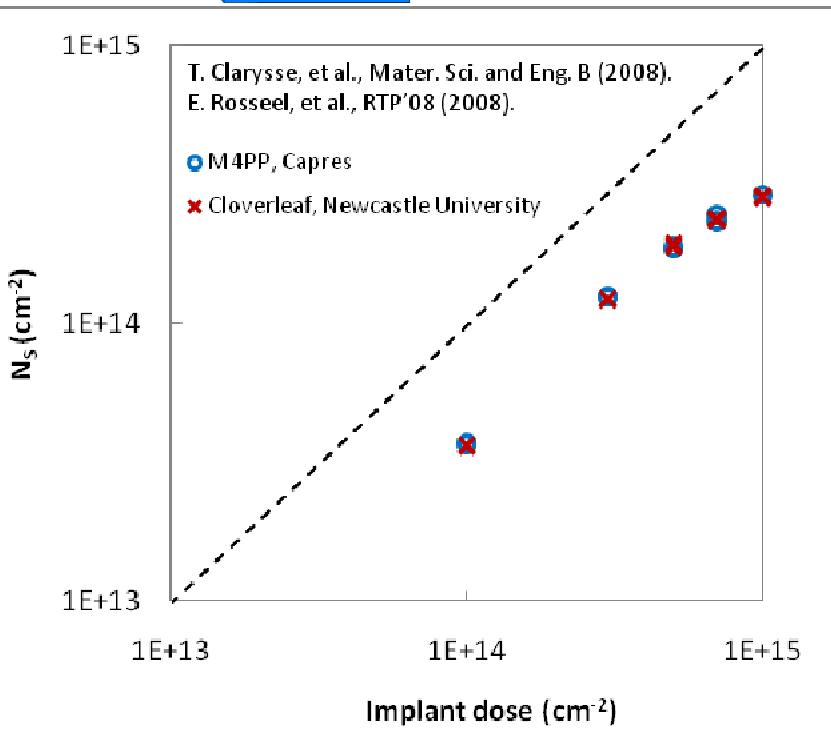
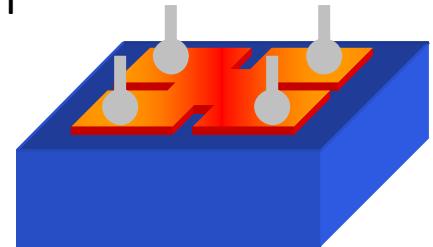


M4PP vs. Cloverleaf patterned Hall



Millisecond laser annealed ultra shallow junction
B doped c-Si (n-type), $r_H = 0.8$

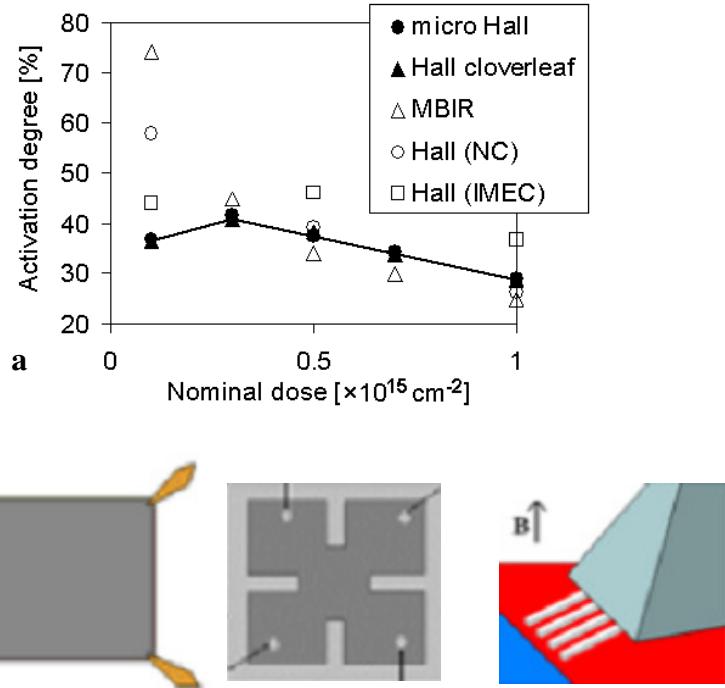
Figures using data from cited references





Micro Hall effect

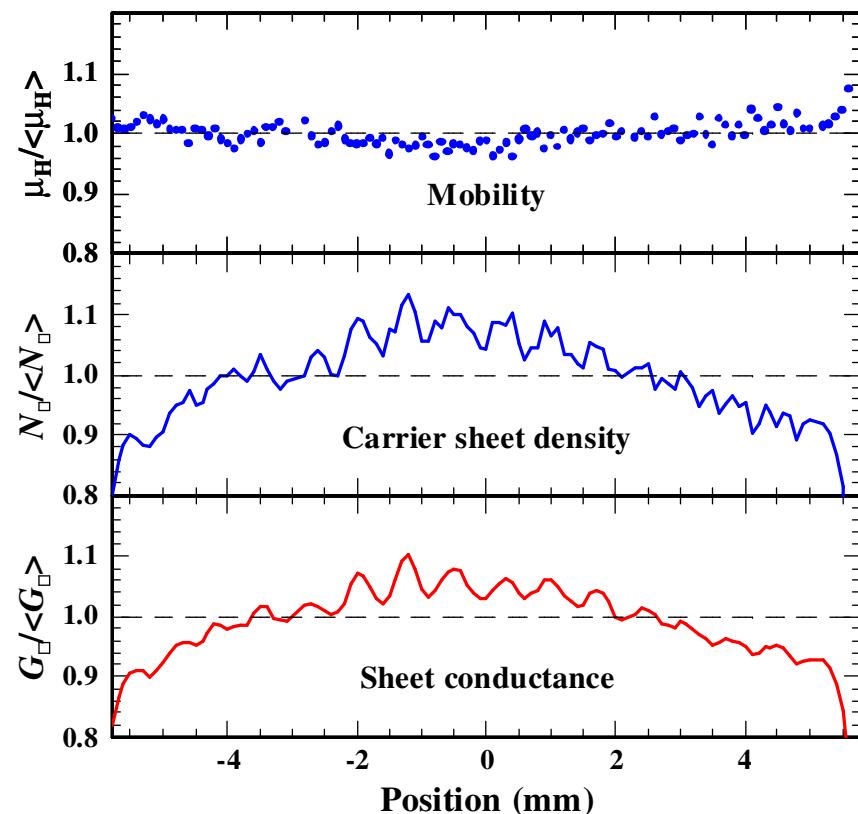
- Reproducibility <1.5%
- Repeatability <1%



T. Clarysse, et al., Mater. Sci. and Eng. B (2008).

D.H. Petersen, et al., J. Appl. Phys. (2008).

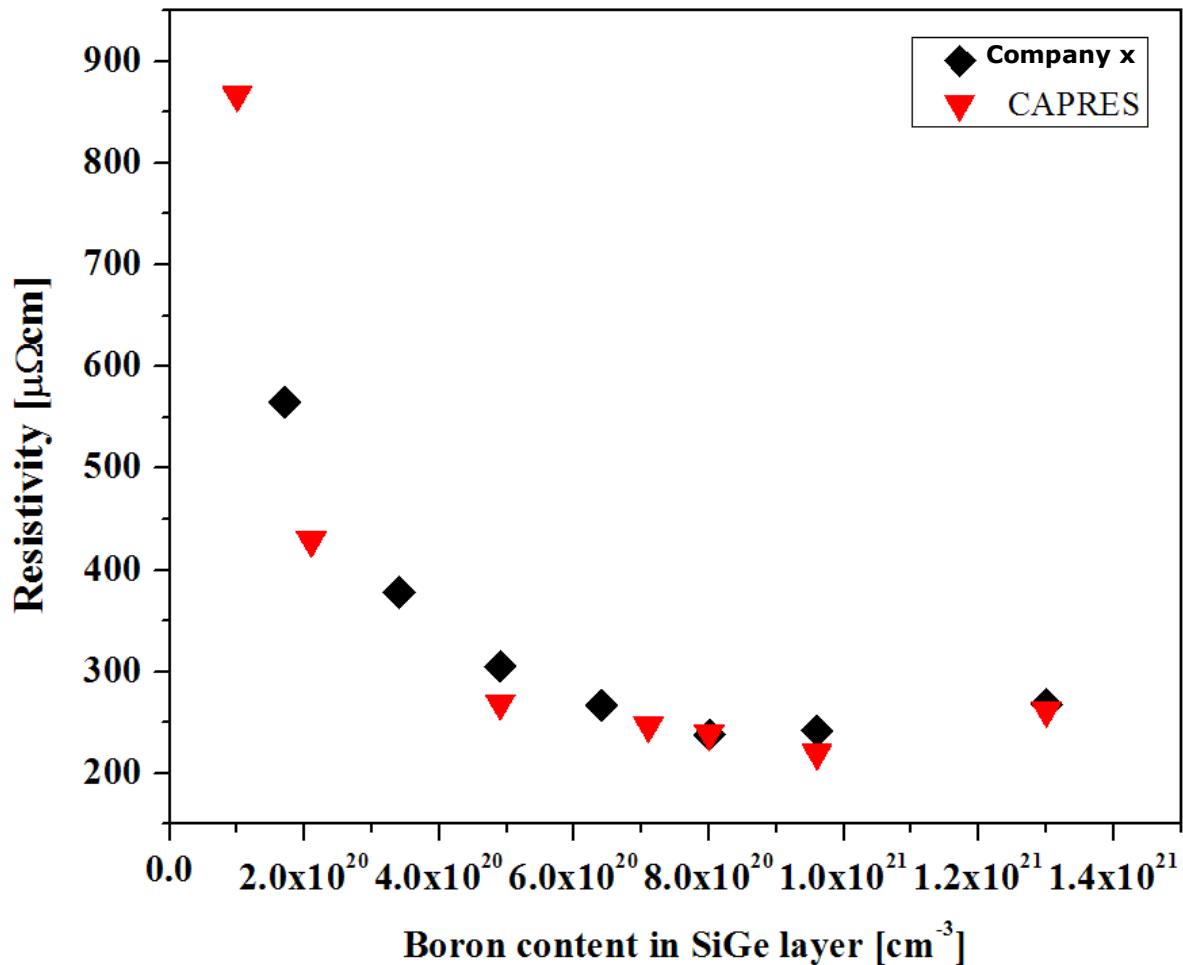
D.H. Petersen, et al., RTP'08 (2008).



E. Rosseel, et al., RTP'08 (2008).

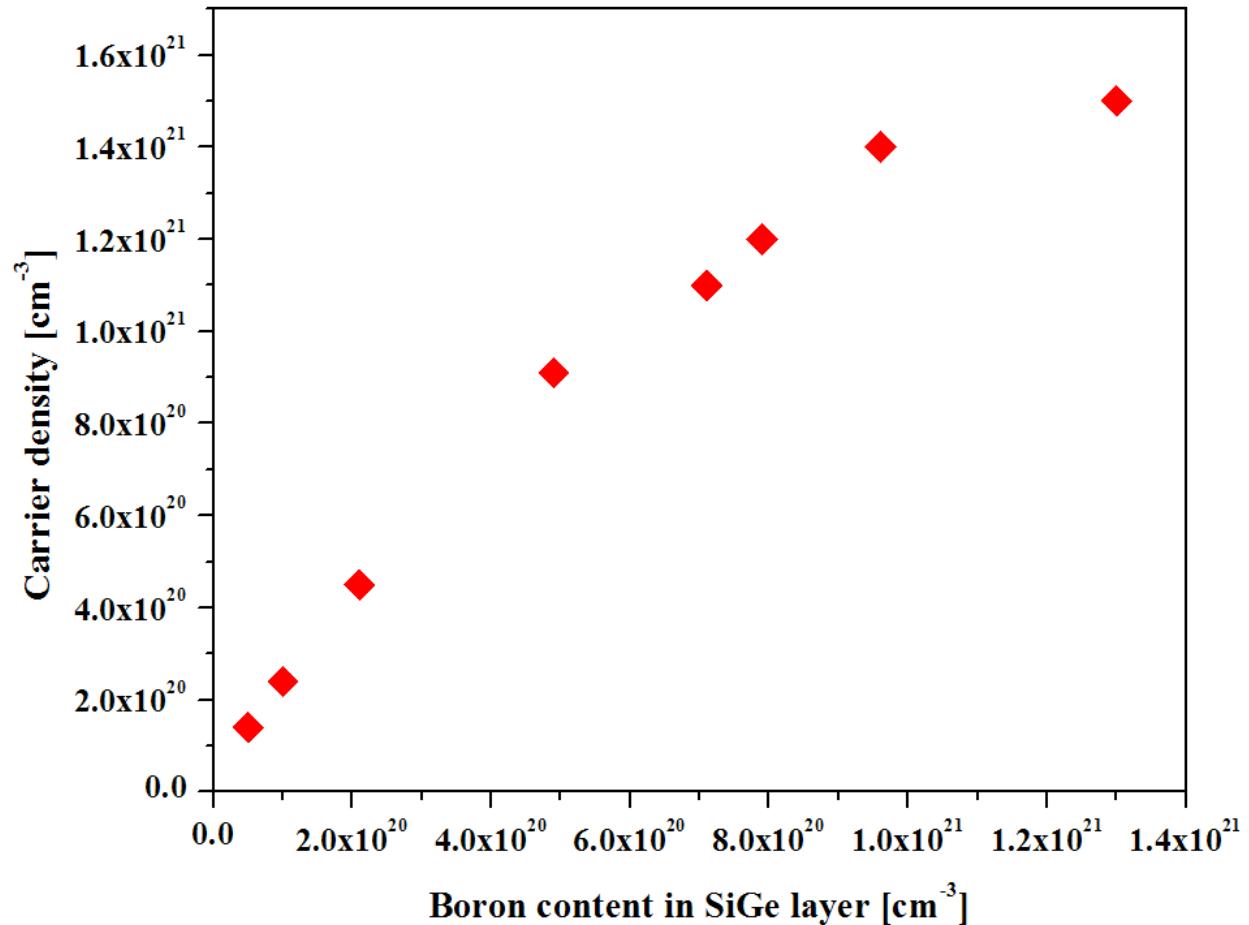


Direct microRs- and micro-Hall mobility measurements on Boron and Carbon Co-doped 60% SiGe layers



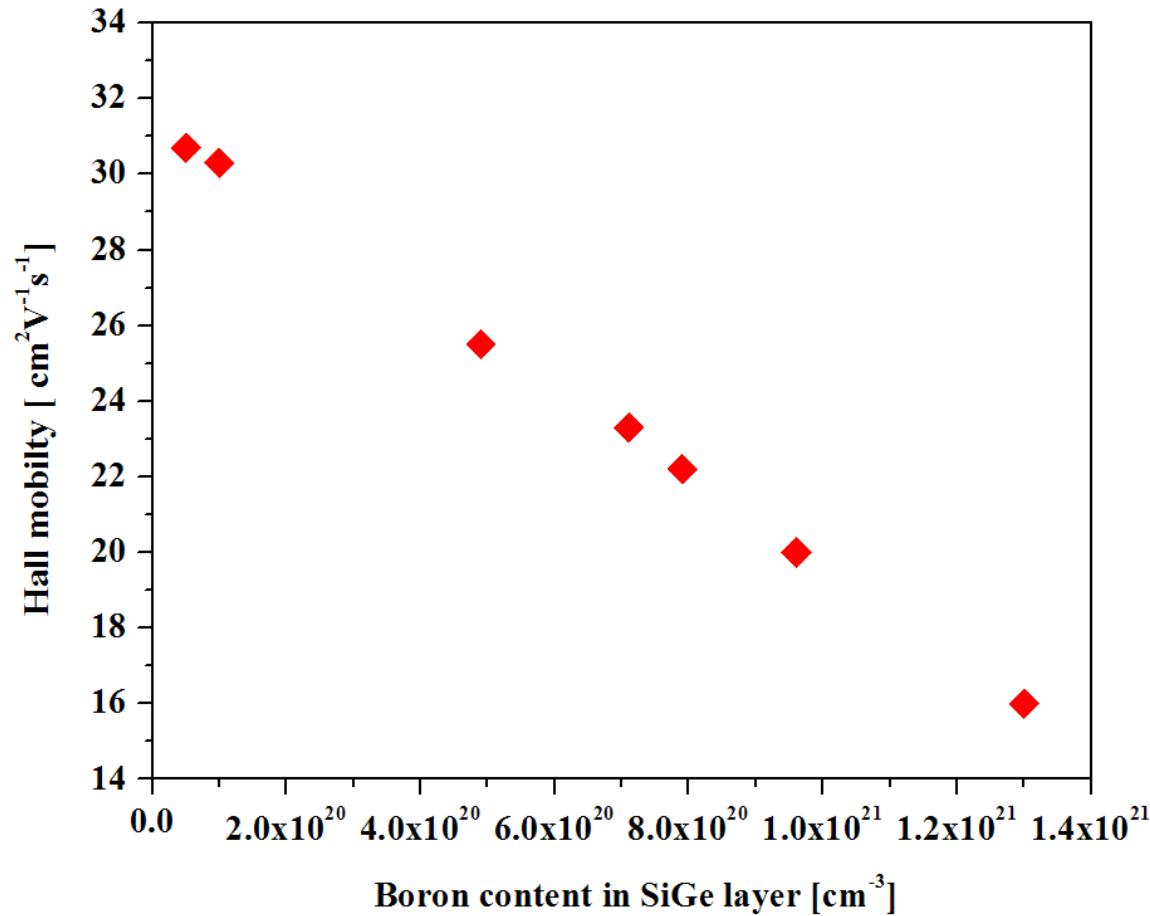


Direct microRs- and micro-Hall mobility measurements on Boron and Carbon Co-doped 60% SiGe layers



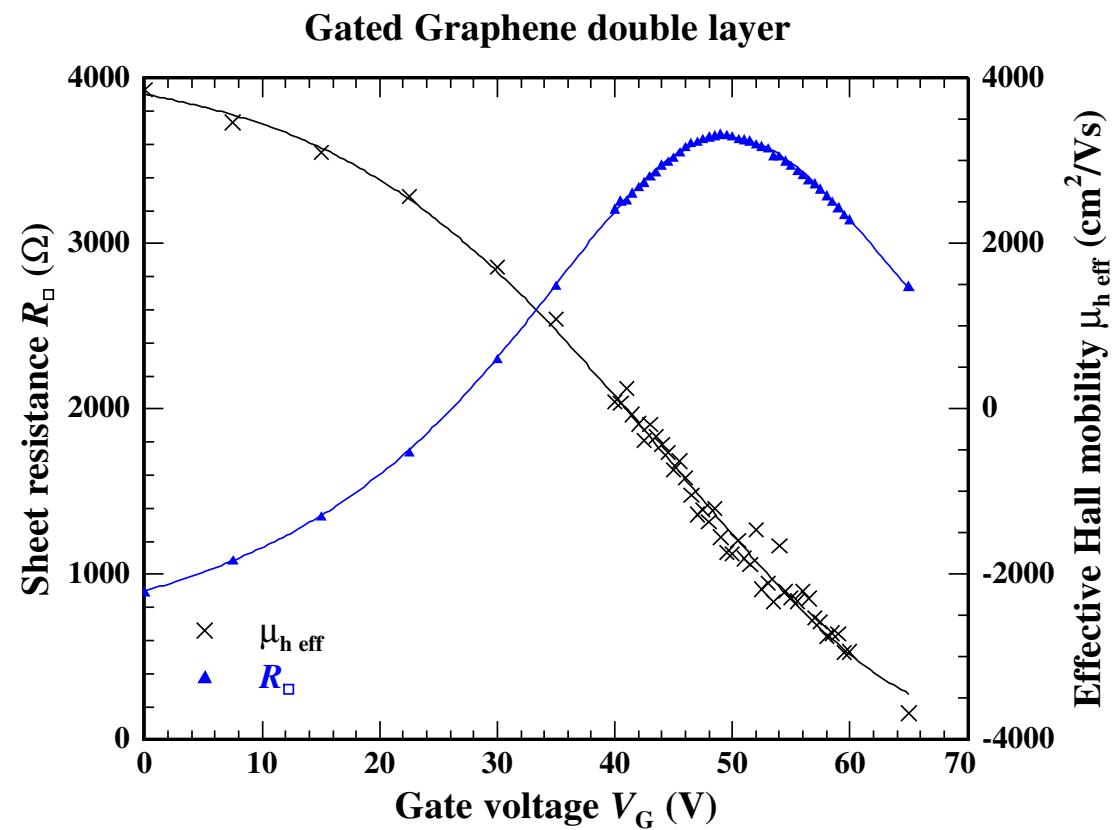
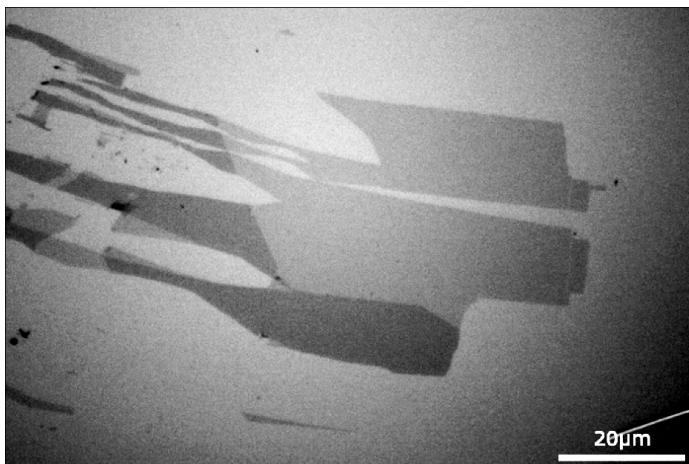
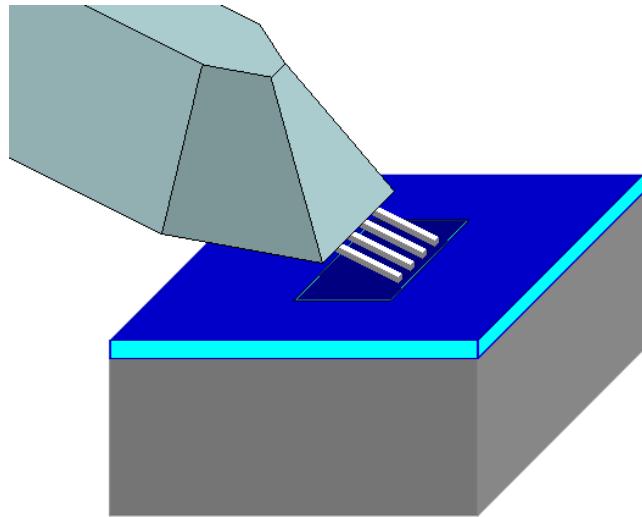


Direct microRs- and micro-Hall mobility measurements on Boron and Carbon Co-doped 60% SiGe layers





Micro Hall effect





Capres Fact-Sheet



- Established in 1999. VC-Fonded.
- More than 45 Fully- and Semi-automatic Tools installed World Wide
- First Fully Automatic MicroRSP-A300 tool installed in 2010
- Six Fully Automatic MicroRSP-A300 tools will be installed in 2012.
- New Semiautomatic 300mm tool including both Rs and Hall-mobility measurement capability ready and installed
- Next application will be direct Leakage Current measurements using the collinear micro-probe. Will be presented at IIT 2012 in Spain



Conclusion

By using M4PP in combination with a high resolution positioning system it is possible to:

- Do direct R_s measurements on small samples**

Enables accurate R_s measurements on e.g scribeline pads

- Measure micron scale variation in R_s**

Enables optimization of the very local sheet resistance

- Micro Hall effect**

Enables fast measurement of the Active Carrier Density and Mobility using the collinear M4PP

- Repeatability, reproducibility**

– R_s : $\sigma < 0.1 \%$

– R_H : $\sigma < 1 \%$



Polarbear at weatherstation Danmarkshavn Northeast Greenland

Photo: Peter Folmer Nielsen

Thank you for your
attention